

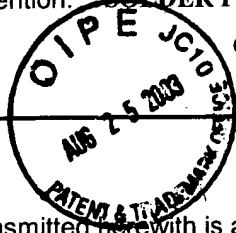
image

1725

AMENDMENT TRANSMITTAL LETTER (Large Entity) Applicant(s): Hiroshi Sakai, et al.	Docket No. 15574
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Serial No. 10/063,915	Filing Date May 23, 2002	Examiner Kevin L. McHenry	Group Art Unit 1725
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Invention: **SOLDER PASTE PRINTING METHOD AND APPARATUS FOR PRINTING SOLDER PASTE**
ON A BOARD ON WHICH WIRING PATTERNS ARE FORMED



TO THE COMMISSIONER FOR PATENTS:

Transmitted herewith is an amendment in the above-identified application.

The fee has been calculated and is transmitted as shown below.

CLAIMS AS AMENDED					
	CLAIMS REMAINING AFTER AMENDMENT	HIGHEST # PREV. PAID FOR	NUMBER EXTRA CLAIMS PRESENT	RATE	ADDITIONAL FEE
TOTAL CLAIMS	6 -	20 =	0 x	\$18.00	\$0.00
INDEP. CLAIMS	2 -	3 =	0 x	\$84.00	\$0.00
Multiple Dependent Claims (check if applicable) <input type="checkbox"/>					\$0.00
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT					\$0.00

- ☒ No additional fee is required for amendment.
- ☐ Please charge Deposit Account No. _____ in the amount of _____
- ☐ A check in the amount of _____ to cover the filing fee is enclosed.
- ☒ The Director is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Deposit Account No. **19-1013/ssmp**
 - ☒ Any additional filing fees required under 37 C.F.R. 1.16.
 - ☒ Any patent application processing fees under 37 CFR 1.17.

[Handwritten Signature]

Signature

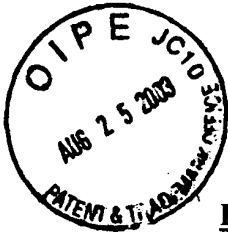
Dated: **August 20, 2003**

Paul J. Esatto, Jr.
Reg. No. 30,749

Correspondence Address
Customer No.: 23389

PJE:AVS:jf
CC:

I certify that this document and fee is being deposited on August 20, 2003 with the U.S. Postal Service as first class mail under 37 C.F.R. 1.8 and is addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.	
<i>[Handwritten Signature]</i>	Signature
Paul J. Esatto, Jr.	
Typed or Printed Name	



PATENTS

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Hiroshi Sakai, et al.	Examiner:	Kevin L. McHenry
Serial No:	10/063,915	Art Unit:	1725
Filed:	May 23, 2002	Docket:	15574
For:	SOLDER PASTE PRINTING METHOD AND APPARATUS FOR PRINTING SOLDER PASTE ON A BOARD ON WHICH WIRING PATTERNS ARE FORMED		Dated: August 20, 2003

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

AMENDMENT AND RESPONSE

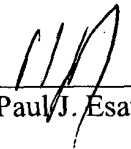
Sir:

In response to the Official Action dated May 20, 2003, Applicants respectfully request reconsideration of the above-identified application in light of the following amendments and remarks:

CERTIFICATE OF MAILING UNDER 37 C.F.R. §1.8(a)

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on August 20, 2003.

Dated: August 20, 2003



Paul J. Esatto, Jr.